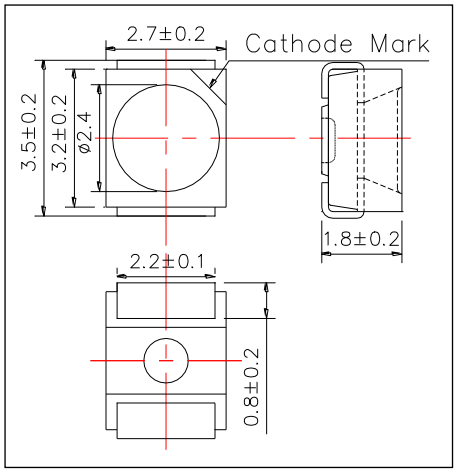
SMT375R
UV TOP LED

SMT375R consists of an InGaN LEDs mounted on the lead frame as TOP LED package and is sealed with silicone resin.
It emits a spectral band of radiation at 375nm.

Outer Dimension (Unit:mm)



<Specifications>

1. Product Name: UV TOP LED
2. Type Number: SMT375R
3. Chip:
   - Chip Material: InGaN
   - Peak Wavelength: 375nm
4. Package
   - Lead Frame Die: Silver Plated
   - Package Resin: PPA Resin
   - Lens: UV Resistant Resin

Absolute Maximum Ratings				
Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	PD	110	mW	Ta=25℃
Forward Current	IF	50	mA	Ta=25℃
Reverse Voltage	VR	5	V	Ta=25℃
Junction Temperature	Tj	120	℃	
Thermal Resistance	Rthja	300	K/W	
Operating Temperature	TOPR	-40 ~ +80	℃	
Storage Temperature	TSTG	-40 ~ +80	℃	
Soldering Temperature*	TSOL	250	℃	

* Soldering condition must be completed within 5 second at 250 ℃.

Electro-Optical Characteristics [Ta=25℃ typ.]						
Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	VF	IF=20mA		3.5	4.3	V
Total Radiated Power*	PO	IF=20mA		6		mW
Radiant Intensity**	IE	IF=20mA		5.0		mW/sr
Brightness	IV	IF=20mA		-		mcd
Peak Wavelength	λP	IF=20mA	370	375	380	nm
Half Width	Δλ	IF=20mA		15		nm
Viewing Half Angle	θ1/2	IF=20mA		±45		deg

* Measured by S3584-08
** Measured by Epitex's designed and AQ2140 & AQ2741

RoHS Compliant

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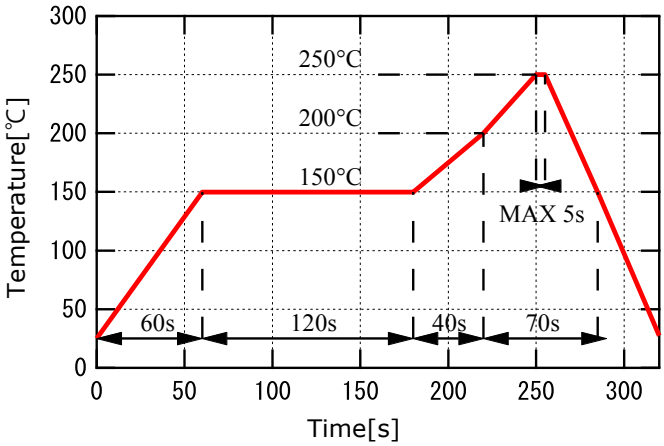
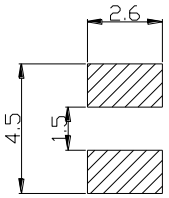
SMD Application

IR-Reflow Soldering Profile for lead free soldering



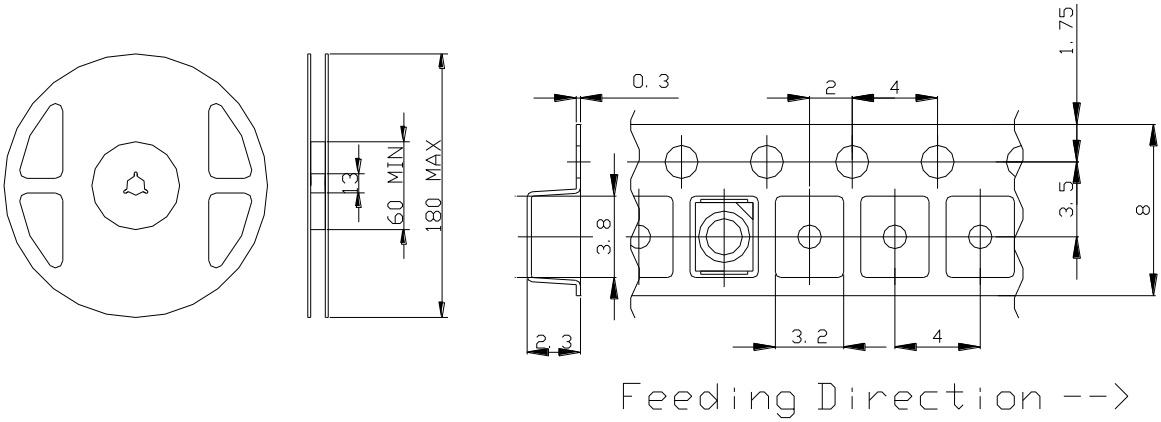
Recommended Land Layout (Unit:mm)



Don’t put stress on SMD and a circuit board after soldering

SMD Packing

Tape and Reel Dimensions (Unit:mm)



Wrapping

Mositure barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.